REMARKS

Reconsideration is requested.

The Examiner is alleging distinction between the subject matter of Group 1 directed to fastened panel and blocks, Group 2 directed to the relationship of blocks and components thickness, Group 3 directed to one-to-one block-package correspondence, and Group 4 directed to pins.

Applicant provisionally elects Group 4 (claims 31-34) for prosecution on the merits.

Applicant reserves the right to file a divisional application directed to the subject matter of the non-elected claims.

This application is now believed to be in immediate condition for allowance, and action to that end is respectfully requested. If the Examiner's next anticipated action is to be anything other than a Notice of Allowance, the undersigned respectfully requests a telephone interview prior to issuance of any such subsequent action. The undersigned is available for telephone consultation at any time during normal business hours (Pacific Time Zone).

Respectfully submitted,

Dated: 7-16-01 By: _____

D. Brent Kenady
Reg. No. 40,045

Application Serial No. 09/687,600
Filing Date ..... October 12, 2001
Inventor ..... Jason E. Tripard
Assignee ..... Micron Technology, Inc.
Group Art Unit 3724
Examiner ..... S. Choi
Attorney's Docket No. MI22-1550
Title: Integrated Circuit Package Separators

VERSION WITH MARKINGS TO SHOW CHANGES MADE ACCOMPANYING RESPONSE TO JUNE 21, 2001 OFFICE ACTION

In the Claims

The claims have been amended as follows. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

Applicant provisionally elects Group 4 for prosecution on the merits.

22. An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:

a panel;

a plurality of blocks over the panel, the blocks having upper surfaces and being configured to support the board while leaving the integrated circuit chip components extending between the block upper surfaces and the panel; and

a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another.

31. The separator of claim 22 further comprising pins extending upwardly from beneath the panel to beyond an upper surface of the panel, the pins configured to extend into the board and retain the board over the panel.

32. The separator of claim 31 wherein the pins do not extend through the panel.

33. The separator of claim 31 further comprising an actuator beneath the panel and configured to vertically displace the panel.

34. The separator of claim 33 wherein the actuator is pneumatically powered.